

# MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

## **BSC066N06NS-MS**

Product specification

## Description

The BSC066N06NS-MS uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

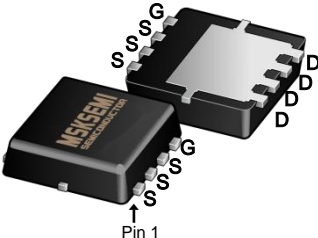
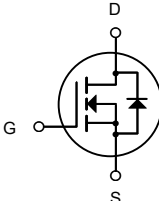

## Features

- $V_{DS} = 60V$   $I_D=80A$
- $R_{DS(ON)} < 7m\Omega$  @  $V_{GS}=10V$

## Application

- Battery protection
- Load switch
- Uninterruptible power supply

## Reference News

DFN5X6-8L	N-Channel MOSFET	Marking
		

## Absolute Maximum Ratings ( $T_c=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_c=25^{\circ}C$	Continuous Drain Current, $V_{GS}$ @ 10V <sup>1</sup>	80	A
$I_D@T_c=100^{\circ}C$	Continuous Drain Current, $V_{GS}$ @ 10V <sup>1</sup>	52	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	320	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	169	mJ
$P_D@T_c=25^{\circ}C$	Total Power Dissipation <sup>4</sup>	108	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^{\circ}C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^{\circ}C$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	1.4	$^{\circ}C/W$

**Electrical Characteristics** ( $T_J=25\text{ }^{\circ}\text{C}$ , unless otherwise specified)

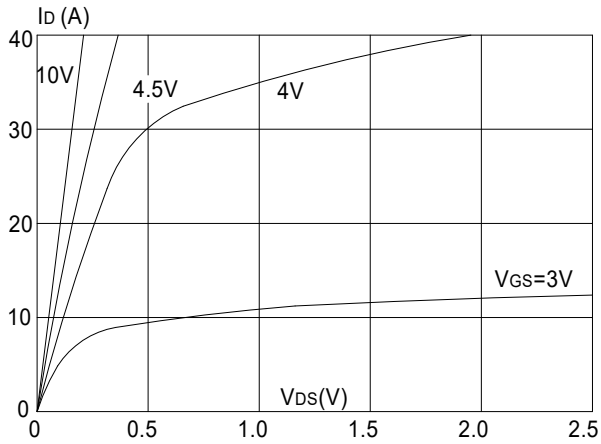
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	60	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V,	-	-	1.0	μA
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V	-	-	±100	nA
On Characteristics						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2	3	4	V
R <sub>DS(on)</sub>	Static Drain-Source on-Resistance <small>note3</small>	V <sub>GS</sub> =10V, I <sub>D</sub> = 30A	-	5.3	7	mΩ
Dynamic Characteristics						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, f=1.0MHz	-	4136	-	pF
C <sub>oss</sub>	Output Capacitance		-	286	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	257	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =30V, I <sub>D</sub> =30A, V <sub>GS</sub> =10V	-	90	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	9	-	nC
Q <sub>gd</sub>	Gate-Drain(“Miller”) Charge		-	18	-	nC
Switching Characteristics						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =30V, I <sub>D</sub> =30A, R <sub>G</sub> =1.8Ω, V <sub>GS</sub> =10V	-	9	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	7	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	40	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	15	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	80	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	320	A
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =30A	-	-	1.2	V
t <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =30A, dI/dt=100A/μs	-	33	-	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge		-	46	-	nC

Notes:

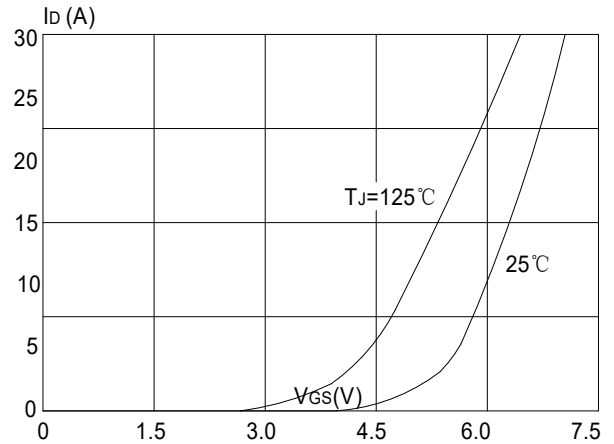
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. EAS condition :  $T_J=25^{\circ}\text{C}$ ,  $V_{DD}=30V$ ,  $V_G=10V$ ,  $L=0.5mH$ ,  $R_g=25\Omega$ ,  $I_{AS}=26A$
3. Pulse Test: Pulse Width $\leq 300\mu s$ , Duty Cycle $\leq 0.5\%$

## Typical Performance Characteristics

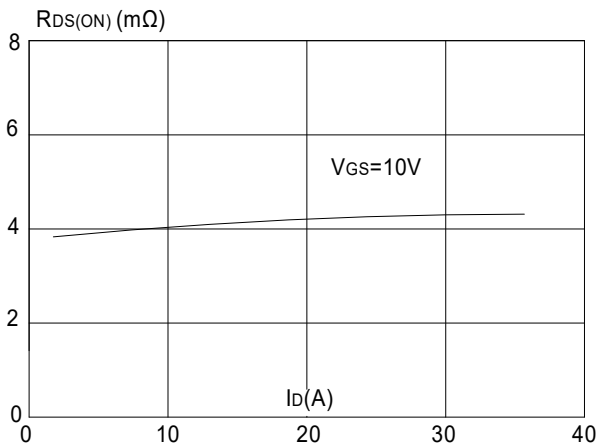
**Figure1:** Output Characteristics



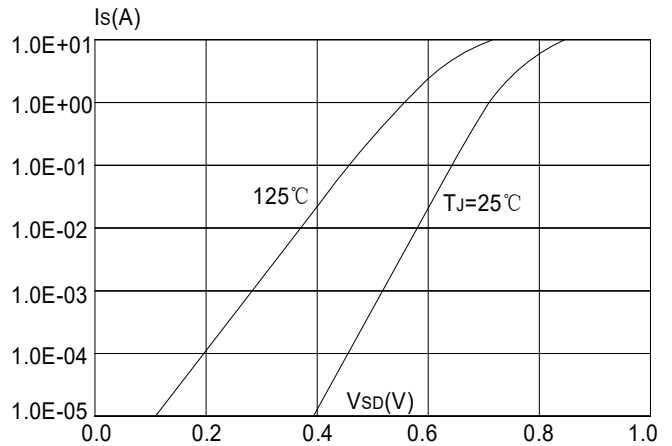
**Figure 2:** Typical Transfer Characteristics



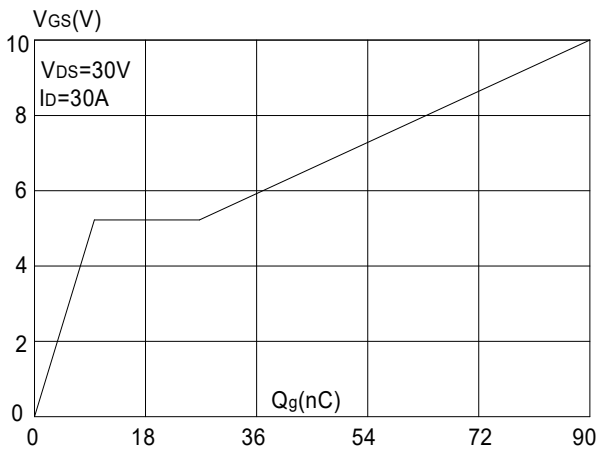
**Figure 3:** On-resistance vs. Drain Current



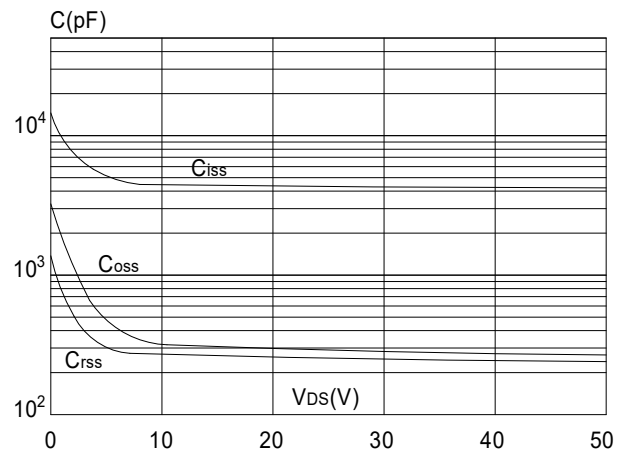
**Figure 4:** Body Diode Characteristics



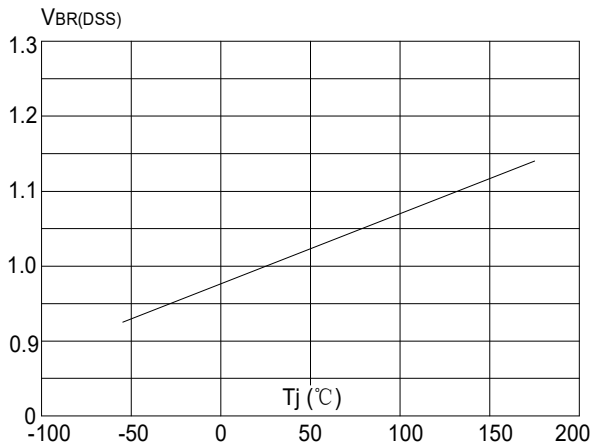
**Figure 5:** Gate Charge Characteristics



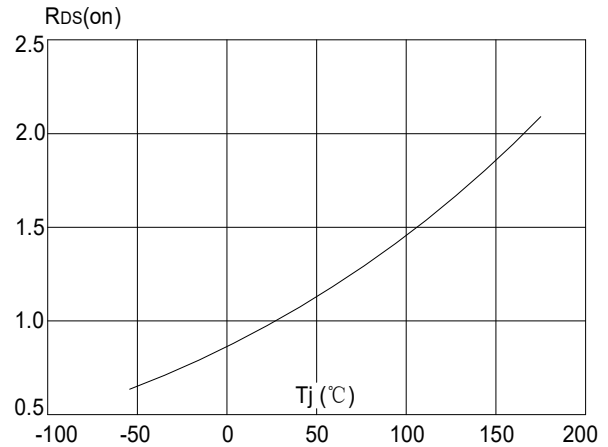
**Figure 6:** Capacitance Characteristics



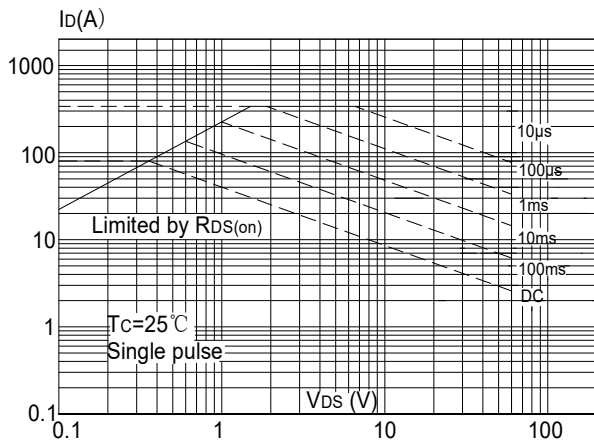
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



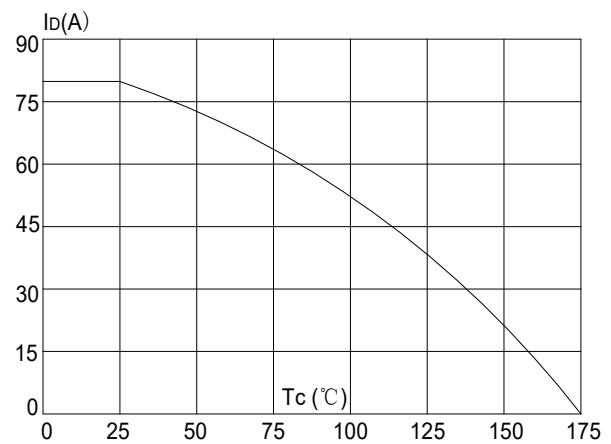
**Figure 8:** Normalized on Resistance vs. Junction Temperature



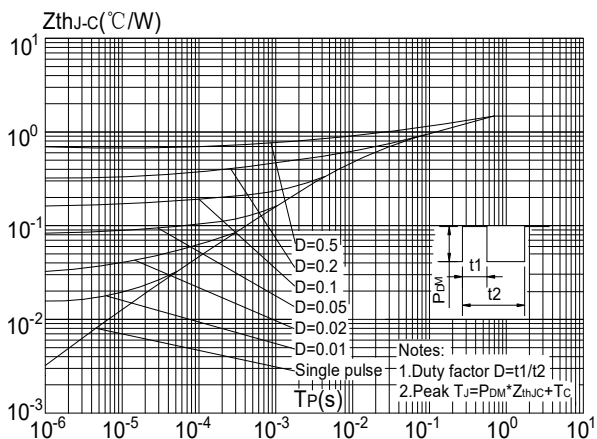
**Figure 9:** Maximum Safe Operating Area



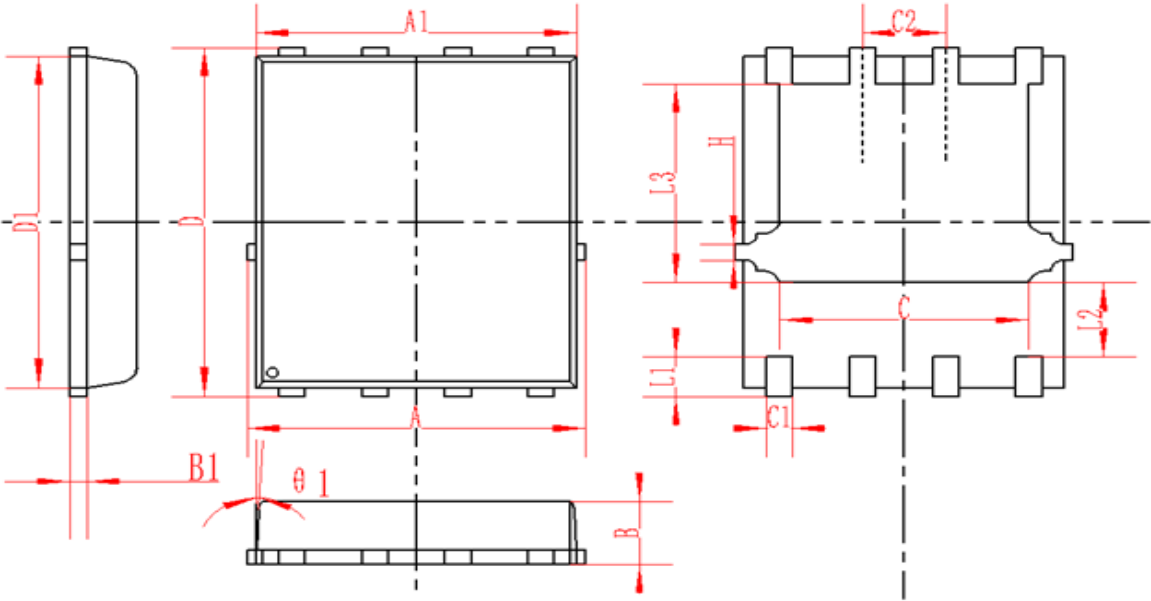
**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature



**Figure.11:** Maximum Effective Transient Thermal Impedance, Junction-to-Case



DFN5X6-8L Package Information



SYMBOL	MM			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	4.95	5	5.05	0.195	0.197	0.199
A1	4.82	4.9	4.98	0.190	0.193	0.196
D	5.98	6	6.02	0.235	0.236	0.237
D1	5.67	5.75	5.83	0.223	0.226	0.230
B	0.9	0.95	1	0.035	0.037	0.039
B1	0.254REF			0.010REF		
C	3.95	4	4.05	0.156	0.157	0.159
C1	0.35	0.4	0.45	0.014	0.016	0.018
C2	1.27TYP			0.5TYP		
θ1	8°	10°	12°	8°	10°	12°
L1	0.63	0.64	0.65	0.025	0.025	0.026
L2	1.2	1.3	1.4	0.047	0.051	0.055
L3	3.415	3.42	3.425	0.134	0.135	0.135
H	0.24	0.25	0.26	0.009	0.010	0.010

REEL SPECIFICATION

P/N	PKG	QTY
BSC066N06NS-MS	DFN5X6-8L	5000

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